



Snap ring thickness of DIAP modules

DESCRIPTION OF CHANGE: Increased height of bushes (snap ring) at mounting location of DIAP low profile modules.

CLASSIFICATION OF CHANGE: Assembly Process/Structure (minor)

REASON FOR CHANGE: To consolidate raw material parts (snap ring) with all other DIAP modules

EXPECTED INFLUENCE ON QUALITY/RELIABILITY/PERFORMANCE:

There will be no effect on the quality, reliability and/or performances.
Minor outline change in form of the module: see details in the next page.
No changes are expected in fit and function of the device in customer's application.

PRODUCT CATEGORY: Modules

PART NUMBERS/SERIES/FAMILIES AFFECTED:

VS-GA300TD60S	VS-GA400TD60S	VS-GT300FD060N
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VISHAY BRAND(s): Vishay Semiconductors

TIME SCHEDULE: Start Shipment Date February 2, 2015

SAMPLE AVAILABILITY: Samples available upon request

PRODUCT IDENTIFICATION: n/a

QUALIFICATION DATA: n/a

This PCN is considered approved, without further notification, unless we receive specific customer concerns before January 19, 2015 or as specified by contract.

ISSUED BY: Fabio Modaro – Product Marketing Manager - Fabio.Modaro@Vishay.com

For further information, please contact your regional Vishay office.

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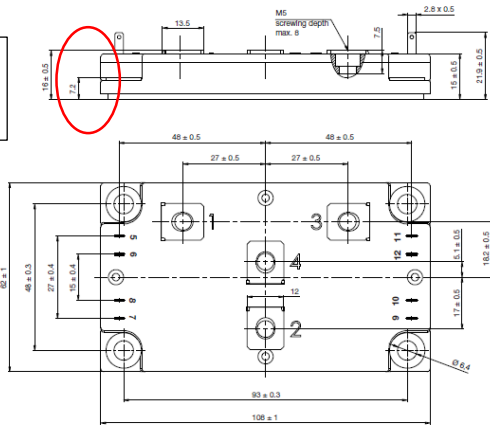
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Description of the changed dimension

DIMENSIONS in millimeters

Before: 6.5 mm (255 mils)
 After: 7.2 mm (283 mils)



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Before: 6.5 mm (255 mils)
 After: 7.2 mm (283 mils)

